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URGENT - EXPIRY OF RULE 34 PERIOD IMMINENT (23 July 2004)

Dear Sirs

INTERNATIONAL BUSINESS MACHINES CORPORATION

Application No: GB 0028820.9

Docket No: END919990008GB1

Following our telephone conversation today, please find enclosed an amended page of the claims of the application. Claim 8 has been amended to include the words "between the first surface and the second arcuate surface" after the words "having a distance".

The applicant submits that the amended application is now in order to proceed to grant. If any point remains unclear, it is requested that the examiner should contact the undersigned on telephone number 01962 815212.

Yours faithfully

C. H. Ling

END919990008GB1

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CLAIMS

1. An electronic package comprising:
an electronic component having a first surface electrically mounted to a substrate and a second arcuate surface having a contour such that the distance between the first surface and the second arcuate surface continually increases from a periphery of the electronic component to the centre of the electronic component and is greatest at the centre of the electronic component; and
an element mounted to the second arcuate surface of the electronic component.
2. The electronic package of claim 1, wherein the element is mounted to the second arcuate surface of the electronic component by an adhesive.
3. The electronic package of claim 2, wherein the adhesive is a thermally conductive reflowable material.
4. The electronic package of claim 1, wherein the element mounted to the second arcuate surface of the electronic component is a cover plate.
5. The electronic package of claim 1, wherein the element mounted to the second arcuate surface of the electronic component is a heat sink.
6. The electronic package of claim 1, wherein the second arcuate surface of the electronic component is contoured using a profiling tool having a concave profiling surface.
7. The electronic package of claim 1, wherein the electronic component has at least one profiled edge.
8. A method of forming an electronic package, comprising the steps of:
providing an electronic component having a first surface and a second surface; and
removing a portion of the second surface such that the second surface is substantially arcuate, having a distance between the first surface and the second arcuate surface which continually increases from a periphery of the electronic component to the centre of the electronic component and is greatest at the centre of the electronic component;
electrically mounting the first surface of the electronic component to a substrate; and
mounting an element to the second surface of the electronic component.